

XIAMETER[®] brand High Consistency Rubber (HCR) Bases – Asia (Excluding Japan) Selection Guide

Product Series	XIAMETER [®] Product Name	Peroxiside Catalyst Type	Cure Profile	Hardness, Shore A	Tensile, MPa	Elongation, %	Tear, kN/m	Plasticity, mm X 100	Compression Set, %	Specific Gravity, g/cm ³	Modulus 100%, MPa	Volume Resistivity, ohm-cm
HCR Bases												
General Purpose – Fumed Silica												
XIAMETER [®] RBB-2000/ RBB-2001 Series	XIAMETER [®] RBB-2000-35 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.1 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	35	7.8	705	13	150	24	1.1	0.6	NA
	XIAMETER [®] RBB-2001-65 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.5 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	71	10.1	320	18	300	18	1.2	2.9	NA
XIAMETER [®] RBB-2002 Series	XIAMETER [®] RBB-2002-30 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1 pph)	Post Cure: 10'/171°C; Post Cure 1h/250°C	35	6	585	10	150	NA	1.09	0.6	NA
	XIAMETER [®] RBB-2002-45 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	48	8.1	445	11	220	NA	1.13	1.1	NA
	XIAMETER [®] RBB-2002-50 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	52	8.8	430	13	260	NA	1.15	1.2	NA
	XIAMETER [®] RBB-2002-70 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1 pph)	Post Cure: 10'/171°C; Post Cure 1h/250°C	67	7.1	490	27	350	NA	1.23	1.6	NA
XIAMETER [®] RBB-2003 Series	XIAMETER [®] RBB-2003-30 Base	RC-4 50P FD (1.0 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	34	7	640	13.7	NA	NA	1.08	NA	NA
	XIAMETER [®] RBB-2003-50 Base	RC-4 50P FD (1.0 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	53	8.5	370	16	NA	25	1.14	NA	NA
	XIAMETER [®] RBB-2003-70 Base	RC-4 50P FD (1.0 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	74	10	380	18	NA	25	1.21	NA	NA
	XIAMETER [®] RBB-2003-80 Base	RC-4 50P FD (1.0 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	83	9.18	320	16.5	NA	NA	1.24	NA	NA
XIAMETER [®] RBB-2004 Series	XIAMETER [®] RBB-2004-40 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	41	9.1	660	31	202	20	1.12	NA	NA
	XIAMETER [®] RBB-2004-50 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	51	10.4	710	26	228	23	1.14	NA	NA
	XIAMETER [®] RBB-2004-60 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	61	9.5	600	26	255	18	1.15	NA	NA

Product Series	XIAMETER® Product Name	Peroxide Catalyst Type	Cure Profile	Hardness, Shore A	Tensile, MPa	Elongation, %	Tear, kN/m	Plasticity, mm X 100	Compression Set, %	Specific Gravity, g/cm³	Modulus 100%, MPa	Volume Resistivity, ohm-cm
General Purpose – Fumed Silica (Continued)												
XIAMETER® RBB-2070 Series	XIAMETER® RBB-2070-40 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	40	7.3	656	22	196	58	1.15	NA	NA
	XIAMETER® RBB-2070-50 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	51	8.7	525	11	218	51	1.15	NA	NA
	XIAMETER® RBB-2070-60 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	60	10	506	17	279	63	1.19	NA	NA
	XIAMETER® RBB-2070-70 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	70	9.5	440	19	297	64	1.21	NA	NA
	XIAMETER® RBB-2070-80 Base	—	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA
XIAMETER® RBB-2100 Series	XIAMETER® RBB-2100-30 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	31	10.0	790	17	NA	55	1.11	NA	NA
	XIAMETER® RBB-2100-40 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	44	9.4	490	17	NA	30	1.11	NA	NA
	XIAMETER® RBB-2100-50 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	51	10.5	450	20	NA	30	1.13	NA	NA
	XIAMETER® RBB-2100-60 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	61	11.0	400	22	NA	30	1.17	NA	NA
	XIAMETER® RBB-2100-70 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	70	10.7	370	24	NA	33	1.20	NA	NA
XIAMETER® RBB-2300-30 Base	XIAMETER® RBB-2300-30 Base	2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 45% active (1 pph)	Press Cure: 10'/171°C;	35	6.6	730	11	190	13	1.1	0.4	NA
XIAMETER® RBB-2400 Series	XIAMETER® RBB-2400-30 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure 4 h/200°C;	36	9.0	750	25.0	NA	40	1.10	NA	NA
	XIAMETER® RBB-2400-50 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure 4 h/200°C;	55	11.0	490	22.0	NA	30.0	1.13	NA	NA
	XIAMETER® RBB-2400-70 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.2 pph)	Press Cure: 5'/116°C; Post Cure 4 h/200°C;	74	11.0	420	24.0	NA	29.0	1.2	NA	NA
General Purpose – PPT Silica												
XIAMETER® RBB-2880 Series	XIAMETER® RBB-2880-30 Base	RC-4 50P FD (0.7 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	30	7.4	670	20 (angle)	NA	NA	1.11	NA	NA
	XIAMETER® RBB-2880-40 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	40	8	560	24 (angle)	NA	NA	1.13	NA	NA
	XIAMETER® RBB-2880-50 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	50	8	400	26 (angle)	NA	NA	1.15	NA	NA
	XIAMETER® RBB-2880-60 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	61	8.5	400	27 (angle)	NA	NA	1.18	NA	NA
	XIAMETER® RBB-2880-70 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	70	8	300	28 (angle)	NA	NA	1.2	NA	NA
	XIAMETER® RBB-2880-80 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	80	7.5	220	22 (angle)	NA	NA	1.22	NA	NA

Product Series	XIAMETER® Product Name	Peroxide Catalyst Type	Cure Profile	Hardness, Shore A	Tensile, MPa	Elongation, %	Tear, kN/m	Plasticity, mm X 100	Compression Set, %	Specific Gravity, g/cm³	Modulus 100%, MPa	Volume Resistivity, ohm-cm
General Purpose – PPT Silica (Continued)												
XIAMETER® RBB-2881 Series	XIAMETER® RBB-2881-30 Base	RC-4 50P FD (0.7 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	32	8	700	20 (angle)	190	NA	1.11	NA	NA
	XIAMETER® RBB-2881-40 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	41	7.5	450	20 (angle)	200	NA	1.13	NA	NA
	XIAMETER® RBB-2881-50 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	52	8.5	400	24 (angle)	240	NA	1.16	NA	NA
	XIAMETER® RBB-2881-60 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	60	8.0	400	24 (angle)	240	NA	1.18	NA	NA
	XIAMETER® RBB-2881-70 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	70	7.0	300	24 (angle)	270	NA	1.20	NA	NA
	XIAMETER® RBB-2881-80 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	82	8.0	170	22 (angle)	320	NA	1.22	NA	NA
XIAMETER® RBB-6600 Series	XIAMETER® RBB-6630-30 Base	RC-4 50P FD (0.75 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	32	7.4	690	18 (angle)	190	NA	1.11	NA	NA
	XIAMETER® RBB-6640-40 Base	RC-4 50P FD (0.65 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	41	8.8	540	22 (angle)	200	NA	1.14	NA	NA
	XIAMETER® RBB-6650-50 Base	RC-4 50P FD (0.6 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	51	8.9	350	21 (angle)	230	NA	1.15	NA	NA
	XIAMETER® RBB-6660-60 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	61	7.5	310	19 (angle)	280	NA	1.23	NA	NA
	XIAMETER® RBB-6661-60 Base	—	NA	NA	NA	NA	NA	NA	NA	NA	NA	NA
	XIAMETER® RBB-6670-70 Base	RC-4 50P FD (0.4pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	69	5.8	300	16 (angle)	285	NA	1.34	NA	NA
	XIAMETER® RBB-6671-70 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	69	8.1	350	24 (angle)	262	NA	1.19	NA	NA
	XIAMETER® RBB-6680-80 Base	RC-4 50P FD (0.4pph) (2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	82	8.7	170	19 (angle)	374	NA	1.33	NA	NA
No Post Cure												
XIAMETER® RBB-2030 Series	XIAMETER® RBB-2030-40 Base	2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 45% active (1 pph)	Press Cure: 10'/171°C;	40	7.2	575	11	150	14	1.11	0.8	NA
	XIAMETER® RBB-2030-80 Base	2,5-bis(tert-butylperoxy) -2,5-dimethylhexane - 45% active (1 pph)	Press Cure: 10'/171°C	85	8	90	15	270	13	1.43	NA	NA

Product Series	XIAMETER® Product Name	Peroxide Catalyst Type	Cure Profile	Hardness, Shore A	Tensile, MPa	Elongation, %	Tear, kN/m	Plasticity, mm X 100	Compression Set, %	Specific Gravity, g/cm³	Modulus 100%, MPa	Volume Resistivity, ohm-cm
High Strength/Tear Resistant												
XIAMETER® RBB-2420 Series	XIAMETER® RBB-2420-40 Base	RC-4 50P FD (1.0 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	40	8.1	600	38	NA	25	1.11	NA	NA
	XIAMETER® RBB-2420-70 Base	RC-4 50P FD (1.0 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	70	9.0	480	38	NA	27	1.19	NA	NA
XIAMETER® RBB-2210 Series	XIAMETER® RBB-2210-30 Base	2,4-dichlorobenzoyl peroxide - 50% active (0.8 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	30	9.1	1120	35	170	32	1.14	0.6	NA
	XIAMETER® RBB-2210-50 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.3 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	50	9	690	34	220	27	1.19	1.2	NA
	XIAMETER® RBB-2210-70 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1.2 pph)	Post Cure: 10'/171°C; Post Cure 4 h/200°C	70	9.9	515	36	290	30	1.22	2.4	NA
XIAMETER® RBB-2220 Series	XIAMETER® RBB-2220-55 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1 pph)	Press Cure: 10'/171°C;	55	10.6	785	51	210	34	1.15	2.1	NA
	XIAMETER® RBB-2220-70 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1 pph)	Press Cure: 10'/171°C	70	8.7	540	51	250	27	1.2	4	NA
Low Temperature												
XIAMETER® RBB-2060 Series	XIAMETER® RBB-2060-40 Base	2,4-dichlorobenzoyl peroxide - 50% active (0.6 pph)	Press Cure: 5'/116°C; Post Cure: 4 h/200°C	40	7.2	625	11	160	18	1.13	0.06	NA
	XIAMETER® RBB-2060-50 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1.0 pph)	Post Cure: 10'/171°C; Post Cure 4 h/200°C	50	8.9	630	32	120	27	1.21	1.2	NA
Wire and Cable												
XIAMETER® RBB-2340 Series	XIAMETER® RBB-2340-50 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.3 pph)	Press Cure: 5'/116°C	50	10.1	465	18	330	NA	1.17	1.3	NA
	XIAMETER® RBB-2340-60 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 45% active (1.0 pph)	Press Cure: 10'/171°C	60	NA	NA	NA	NA	NA	NA	NA	NA
	XIAMETER® RBB-2340-70 Base	2,4-dichlorobenzoyl peroxide - 50% active (1.5 pph)	Press Cure: 5'/121°C	70	9.9	375	19	350	NA	1.2	2.4	NA
Conductive												
	XIAMETER® RBB-6200-70 Base	2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active (2.0 pph)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	78	NA	NA	NA	NA	NA	1.20	NA	2.0
Flame Retardant												
	XIAMETER® RBB-6300-50 Base	RC-4 50P FD (0.5 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active) and SRX 557 U (0.4 pph)	Press Cure: 10'/160°C; Post Cure: 4 h/200°C	54	7.3	520	23 (angle)	260	NA	1.36	NA	NA
Steam Resistant												
	XIAMETER® RBB-6410-50 Base	RC-4 50P FD (0.8 pph) (2,5-bis(tert-butylperoxy)-2,5-dimethylhexane - 50% active)	Press Cure: 10'/170°C; Post Cure: 4 h/200°C	50	9.3	480	10	250	NA	1.15	NA	NA

Typical Properties – Specification Writers: These values are not intended for use in preparing specifications. Please contact your local XIAMETER® sales representative prior to writing specifications on these products.

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Printed in USA

AGP11096

Form No. 95-750-01

